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ABSTRACT

2 A thin type ball grid array package is provided. A composite substrate for the
3 package is consisted of a wiring board and a dummy die. The wiring board has an
4 opening through upper and lower surfaces thereof. The dummy chip is attached to one
5 surface of the wiring board, and covers the opening to form a chip cavity for
6 accommodating an integrated circuit chip. The wiring board has a step with a plurality
7 of connecting pads in the opening. The integrated circuit chip is attached to the dummy
8 die and electrically connected to the connecting pads of the wiring board. A package
9 body is formed in the chip cavity.

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